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IC Socket Type: **LGA 3647**

Connector System: **Board-to-Board**

Number of Positions: **3647**

Contact Mating Area Plating Material Thickness: [**30 μin**]

Centerline (Pitch): **.86 mm, .99 mm [.034 in, .039 in]**

[All LGA 3647 Sockets \(8\)](#)

Features

Product Type Features

Connector System	Board-to-Board
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Number of Positions	3647
Grid Spacing	.9906 x .8585 mm [.039 x .0338 in]

Body Features

Frame Style	Square
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Contact Features

Contact Mating Area Plating Material	Gold
Contact Base Material	Copper Alloy
IC Socket Type	LGA 3647
	30 μin
Contact Current Rating (Max)	.5 A

Mechanical Attachment

PCB Mounting Style	Surface Mount Solder Ball
Connector Mounting Type	Board Mount

Housing Features



Housing Material	High Temperature Thermoplastic
Housing Color	Black
Centerline (Pitch)	.86 mm, .99 mm [.034 in][.039 in]

Usage Conditions

Operating Temperature Range	-25 – 100 °C [-13 – 212 °F]
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Operation/Application

Circuit Application	Signal
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Method	Tray
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Other

Socket Connector Comment	Lead-Free Solderball
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides

on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Documents

Product Drawings

[LGA3647-1 SOCKET-P1 KIT FOR ODM \(30U AU\)](#)

English

CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_2-2822979-4_C.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2-2822979-4_C.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2-2822979-4_C.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

[LGA 3647 Socket Product Flyer](#)

English



[Product Specifications](#)

[Application Specification](#)

English